

In this regard, the Office Action asserts that Mandai cures the deficiencies of the combination of Hagn and Ikata. The Office Action asserts that "Mandai discloses that a duplexer 10 (see Fig. 3) includes a chip or two chips including acoustic wave elements 13 (see paragraphs [0013] and [0034]), and mounted on a multi-layer substrate 15, and the multi-layer substrate 15 includes components of the duplexer except the acoustic wave elements (see paragraphs [0013] and [0034])." We disagree.

Mandai's multi-layer substrate 15 is a substrate for the duplexer 10 alone (see Fig. 3). In contrast, the multi-layer substrate recited in claims 6 and 7 is a substrate for integrating the first separating means, the second separating means and the duplexer, not for the duplexer alone.

Thus, Mandai's substrate is clearly different from the claimed multi-layer substrate for integrating the first separating means, the second separating means and the duplexer. Mandai therefore fails to disclose the claimed feature that the multi-layer substrate for integrating the first separating means, the second separating means and the duplexer includes components of the duplexer except the acoustic wave elements.

In particular, Mandai merely discloses that the multi-layer substrate 15 for the duplexer alone includes components of the duplexer except the acoustic wave elements. Thus, Mandai does not disclose "a single multi-layer substrate for integrating the first separating means, the second separating means and the duplexer," and "the multi-layer substrate includes components of the duplexer except the acoustic wave elements," as recited in claims 6 and 7.

Therefore, combining the above disclosure of Mandai with the modified Hagn would merely provide such a configuration that Mandai's duplexer 10, which includes the substrate 15 for the duplexer 10 alone, with a surface acoustic wave filter 13 mounted on the substrate 15 (see Fig. 3), is mounted on the multi-layer substrate of the modified Hagn. Such a

configuration is clearly different from the configuration claimed in claims 6 and 7. Also, miniaturization of the module cannot be achieved with the configuration of the modified Hagn combined with Mandai.

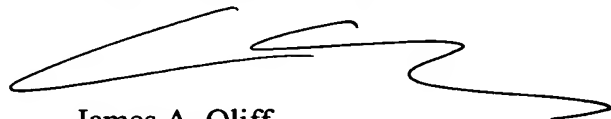
For example, the configuration of the modified Hagn combined with Mandai would be as shown in Fig. 9 of the present application. In contrast, Fig. 10 and Fig. 11 of the present application show the configurations according to claims 6 and 7, respectively. The distinction of the claimed invention over the modified Hagn combined with Mandai can be clearly seen by comparing Fig. 9 with Figs. 10 and 11.

For at least the above reasons, withdrawal of the rejection of claims 6 and 7 under 35 U.S.C. §103(a) is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 6 and 7 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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